

Ant Part No.	LEC	Lens Colour	
	Material	Emitting Colour	Lens Colour
703-1042	InGaN / Sapphire	White	Yellow diffused

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Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation*	PD	120	℃
Reverse Voltage*	V R	5	V
D.C. Forward Current*	If	30	mA
Pulsed Forward Current (1 / 10 Duty Cycle, 0.1ms Pulse Width)*	If (Peak)	100	mA
Operating Temperature Range	Topr.	-40 to +100	℃
Storage Temperature Range	Tstg.	-40 to +100	℃
Soldering Temperature*	Tsld.	Reflow Soldering: 260°C for 10sec. Hand Soldering: 350°C for 3sec.	
Electric Static Discharge Threshold (HBM)*	ESD	6000	V

^{*}The values are based on 1 die performance.

Electrical & Optical Characteristics: Hyper Red

Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity*2		lv	If=20mA*3	4800	11480		mcd
Luminous Flux*2		Фи	If=20mA*3		25890		lm
Forward Voltage*3		Vf	If=20mA*3		3.2	4.0	V
	WA		If=20mA*1	5000		5250	_ к
Correlated Colour	WB			5250		5500	
Temperature*2	WC	CCT		5500		5750	
	WD			5750		6000	
Colour Rendering Index (Ra)		CRI	If=20mA*3		64		Ra
Reverse Current*1		lr	Vr=5V*3			50	μΑ
Viewing Angle*2		2θ½	If=20mA*3		120		deg

Notes: 1. The data is tested by an IS tester.

- 2. Customer's special requirements are also welcome.
- 3. * For each die.
- 4. *2 When all LED dies are operated simultaneously.
- 5. *3 For one circuit.

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Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)



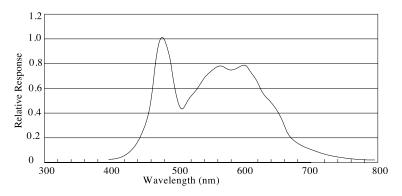
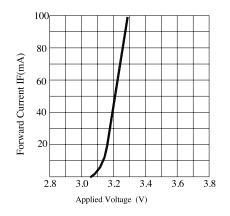
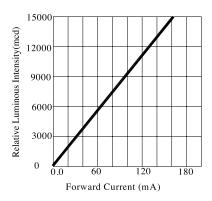
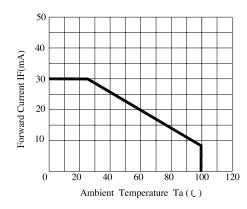


Fig1. WHITE LED Spectrum VS. WAVELENGTH

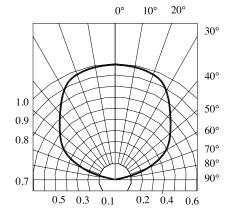




Forward Current VS. Applied Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature VS. Forward Current

Radiation Diagram

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Recommended Storage Environment:

- Temperature: 5°C ~ 30°C (41°F ~ 86°F)
- Humidity: 60% RH Max.
- Use within 7 days after opening of sealed vapour/ESD barrier bags.

If moisture absorbent material (silica gel) has faded away or LEDs have exceeded the storage time, baking treatment should be performed using the following conditions:

- Baking Treatment: 60 ± 5°C for 24 hours
- Fold the opened bag firmly and keep in dry environment.

Soldering

Reflow Soldering			Hand Soldering		
	Lead Solder	Lead-free Solder			
Pre-heat	12~150°C	180~200°C	Temperature	350°C Max.	
Pre-heat Time	120sec. Max.	120sec. Max			
Peak Temperature	240°C Max.	260°C Max.]	3sec. Max (one time only)	
Soldering Time	10sec Max.	10sec. Max	Soldering Time		
Condition	Refer to Temperature profile 1	Refer to Temperature profile 2		(one time only)	

^{*}After reflow soldering rapid cooling should be avoided.

Temperature-profile (surface of circuit board)

Use the conditions shown under figure.

<1: Lead Solder> <2: Lead-free Solder> 240°C Max. 260°C Max. 1~5°C/sec. 2.5~5°C/sec. 10sec. Max. 10sec. Max. Pre-heating Pre-heating 180~200°C 120~150°C 60sec. Max. 60sec. Max. 120sec. Max 120sec. Max. 1~5°C/sec. 2.5~5°C/sec. **Recommended Soldering Pad Design** Use the conditions shown under figure.

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